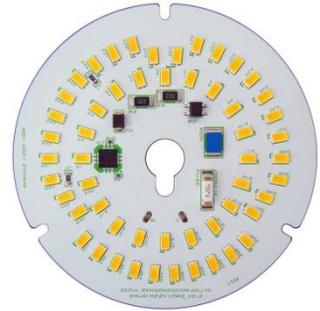


Acrich Module with Industry Leading Efficacy

Acrich2 – 10W

SMJD-HE2V10W3



Product Brief

Description

- The Acrich2 series of products are designed to be driven directly off of AC line voltage, therefore they do not need the standard converter essential for conventional general lighting products.
- The converter or driver found in most general lighting products can limit the overall life of the product, but with the Acrich2 series of products the life of the product can more closely be estimated from the LED itself. This will also allow for a much smaller form factor from an overall fixture design allowing for higher creativity in the fixture.
- The modules have a high power factor which can contribute to a higher energy savings in the end application.

Features and Benefits

- High Efficacy up to 140 lm/W
- Connects directly to AC line voltage
- High Power Factor
- Low THD
- Long Life Time
- Simple BOM
- RoHS Compliant

Key Applications

- Ceiling light
- Flush mount

Table 1. Product Selection

Part No.	Vin [Vac]	P [W]	CCT [K]	Flux [lm]		CRI
				Min.	Typ.	Min.
SMJD-HE2V10W3	120	10	4700-5300	1250	1350	70
			2600-3200	1100	1200	80

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Performance Characteristics

Table 2. Electro Optical Characteristics, T_a = 25°C

Parameter	Symbol	Value			Unit	Mark
		Min.	Typ.	Max.		
Luminous Flux	Φ_V [2]	1250	1350	1450	lm	C
		1100	1200	1300		G, H
Correlated Color Temperature [3]	CCT	4700	5000	5300	K	C
		2900	3000	3200		G
		2600	2700	2900		H
CRI	Ra	70	-	-	-	C
		80				G, H
Input Voltage [4]	V _{in}		120		Vac	2V
Power Consumption	P	9	10	11	W	10W
Operating Frequency	f		50 / 60		Hz	
Power Factor	PF		Over 0.97		-	
Viewing Angle	2 $\Theta_{1/2}$		120		deg.	
Tolerance of Surge [5]	V _s	500	-	-	V	
Transient Protection [6]	V _s	2500	-	-	V	

Notes :

- (1) At 120Vac, T_a = 25°C
- (2) Φ_V is the total luminous flux output measured with an integrated sphere.
- (3) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
- (4) Operating Voltage doesn't indicate the maximum voltage which customers use but means tolerable voltage according to each country's voltage variation rate. It is recommended that the solder pad temperature should be below 70 °C.
- (5) Surge withstand in accordance with IEC61000-4-5
- (6) Seven strikes, 100kHz 2.5KV in accordance with ANSI/IEEE C62.41.2-2002 Category A operation

Performance Characteristics

Table 3. Absolute Maximum Ratings, $T_a = 25^{\circ}\text{C}$, 220Vac

Parameter	Symbol	Unit	Value
Maximum Input Voltage	V_{in}	Vac	144
Power Consumption	P	W	12.5
Operating Temperature	T_{opr}	$^{\circ}\text{C}$	-30 ~ 85
Storage Temperature	T_{stg}	$^{\circ}\text{C}$	-40 ~ 100
ESD Sensitivity	-	-	$\pm 4,000\text{V HBM}$

Thermal Resistance

Part	Package Power Dissipation [W]	Maximum Junction Temperature [°C]	R θ_{js} [°C/W]
Acrich2 LED	SAW8KG0B Max 0.58	125	27
Acrich2 IC	Max 1.0	150	11.25

The Acrich2 LED has a thermal resistance of 27 °C/W from junction of the LED to the LED lead.

The maximum junction temperature of the Acrich2 LED package is 125 °C, therefore the maximum lead temperature T_{s_max} is

$$\begin{aligned}
 T_{s_max} &= T_{j_max} - (R\theta_{js} * P_d) \\
 &= 125\text{ °C} - (27\text{ °C/W} * 0.58\text{W}) = 109.34\text{ °C}
 \end{aligned}$$

Although this is the maximum lead temperature, it is recommended to keep the lead temperature under 70 °C.

The Acrich2 IC has a 11.25 °C/W thermal resistance from junction to the top surface.

The maximum junction temperature (T_{j_max}) of the IC is 150 °C, therefore the maximum temperature of the top of the IC is

$$\begin{aligned}
 T_{t_max} &= T_{j_max} - (R\theta_{jt} * P_d) \\
 &= 150\text{ °C} - (11.25\text{ °C/W} * 1.0\text{W}) = 138.75\text{ °C}
 \end{aligned}$$

Relative Spectral Distribution

Fig 1. Relative Spectral Distribution vs. Wavelength Characteristic – G, H

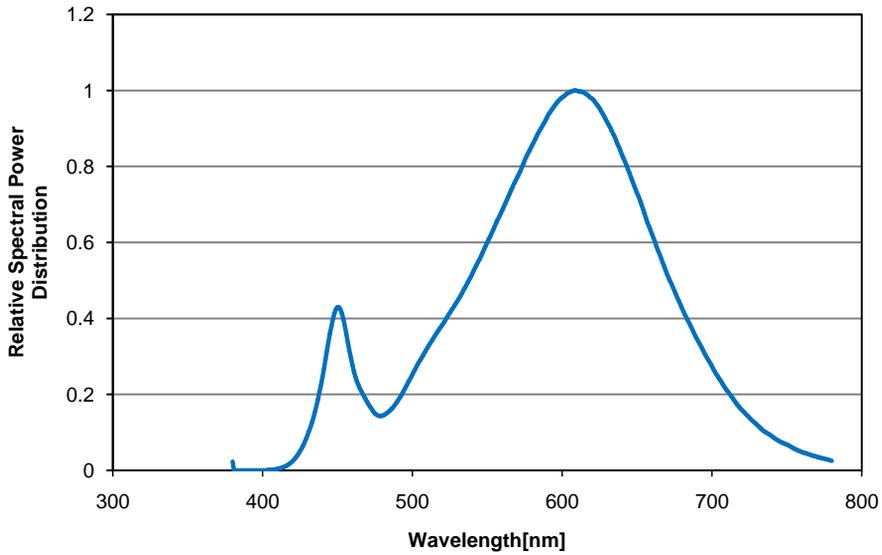
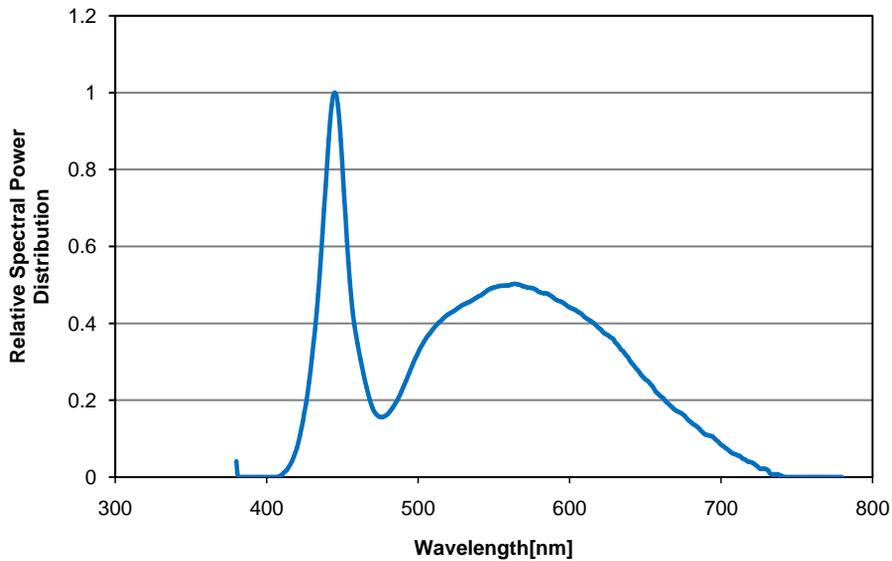
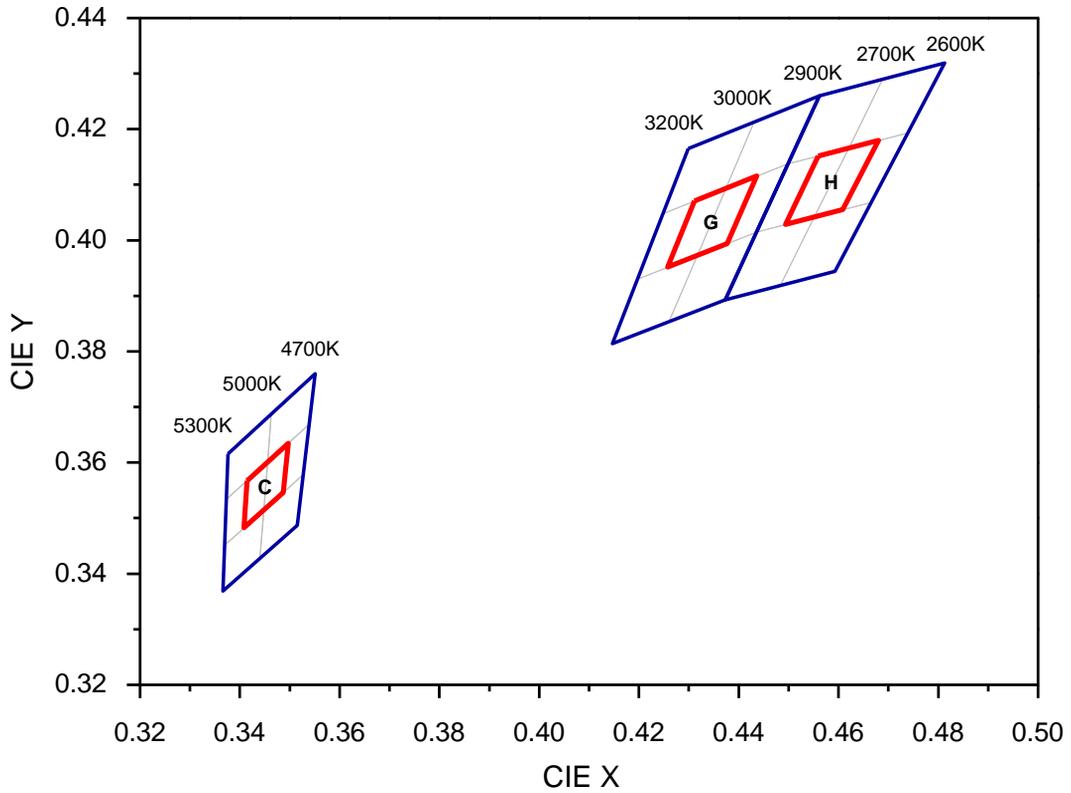


Fig 2. Relative Spectral Distribution vs. Wavelength Characteristic – C



Color Bin Structure



Bin code	X	Y	Bin code	X	Y	Bin code	X	Y
C	0.3415	0.3568	G	0.4311	0.4071	H	0.4560	0.4152
	0.3409	0.3483		0.4258	0.3952		0.4494	0.4029
	0.3487	0.3546		0.4377	0.3994		0.4609	0.4056
	0.3498	0.3635		0.4437	0.4116		0.4680	0.4180

Part List

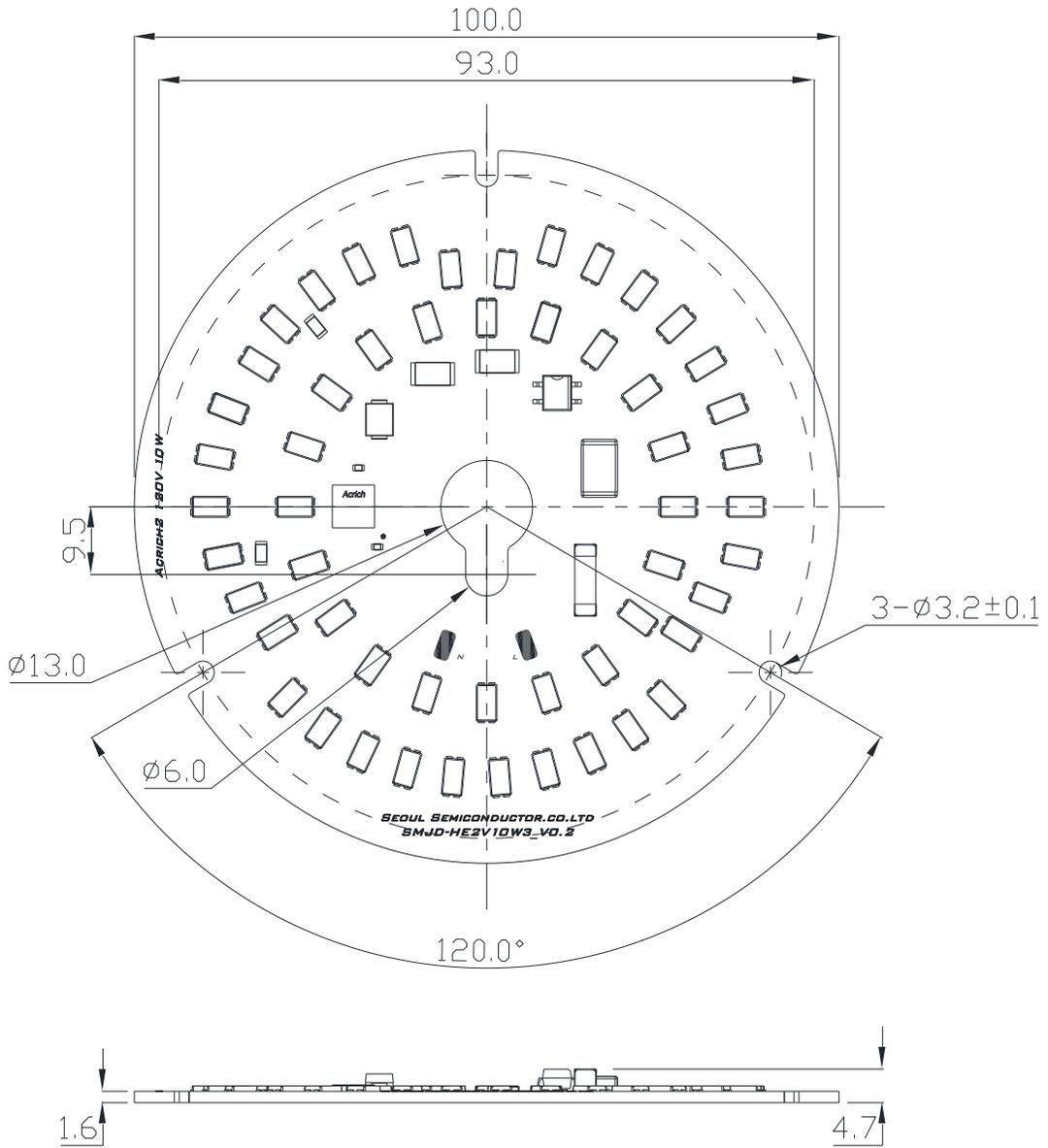
Table 4. Part List

No	Part	Reference	Specification	Quantity
1	PCB	-	Al, $\Phi=100$, T=1.6, 1 layer / Cu 1oz / White PSR	1
2	LED	D1~D54	SAW8KG0B	54
3	IC	U1	DT3001B	1
4	Fuse	FUSE	250V, 1A	1
5	Varistor	MOV	275Vac	1
6	Bridge Diode	BD	600V, 1A	1
7	TVS	ZN	440V, 600W, 5%, Unidirectional	1
8	Resistor	R3~R4	R6432, 22 Ω , 5%(J)	2
9	Resistor	RS	R1608, 2k Ω , 1%(F)	1
10	Resistor	BLD	R1608, 1k Ω , 5%(J)	1
11	Resistor	J1~J2	R3216, 0 Ω , 5%(J)	2

Notes :

- (1) The above specification is subject to change without further notice for the improvement of products.

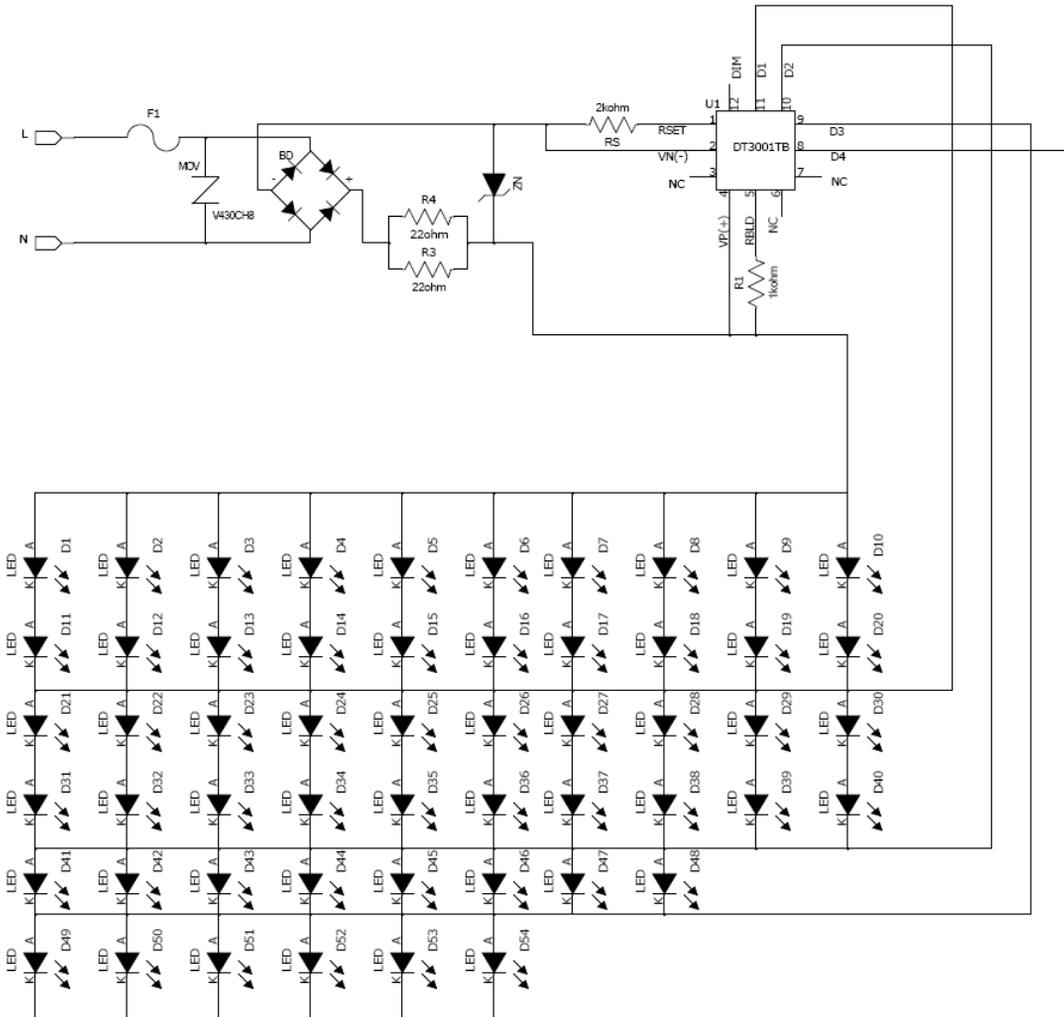
Mechanical Dimensions



Notes :

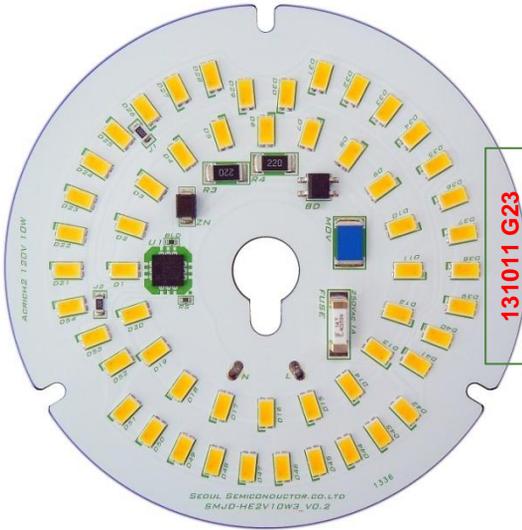
- (1) All dimensions are in millimeters. (Tolerance unless noted : ± 0.2)
- (2) Scale : None

Circuit Drawing



SMJD-HE2V10W3 (120V)

Marking Information



• 10 Digits(including Blank)

131011 G 2 3
 ① ② ③ ④

- ① SMT Date(6 Digits) – ex)130109
- ② CCT(1 Digit)
- ③ CCT Combination No.(1 Digit)
- ④ Vf Combination No.(1 Digit)

* Marking is based on SMJD-HE2V10W3

② CCT

Marking	CCT[K]		
	Min	Typ	Max
B	5300	5600	6000
C	4700	5000	5300
E	3700	4000	4200
G	2900	3000	3200
H	2600	2700	2900

③ CCT Combination No.

Marking	Bin 1	Bin 2
1	0	5
2	5	0
3	1	4
4	4	1
5	2	3
6	3	2
7	M2	M3
8	M3	M2
9	M2	3
A	3	M2
B	M3	2
C	2	M3
D	M2	M2
E	M3	M3

④ Vf Combination No.

Marking	Bin 1	Bin 2
1	A	A
2	A	B
3	B	A
4	A	C
5	C	A
6	B	B
7	B	C
8	C	B
9	C	C

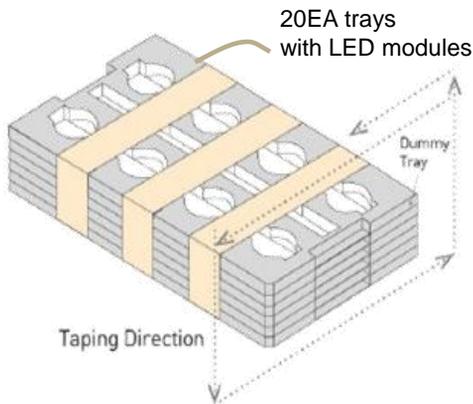
Packing

1. Tray information



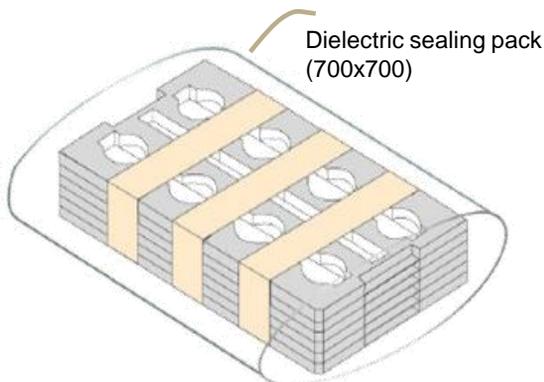
- 8 PCS LED modules packed per tray

2. Tray stack and taping

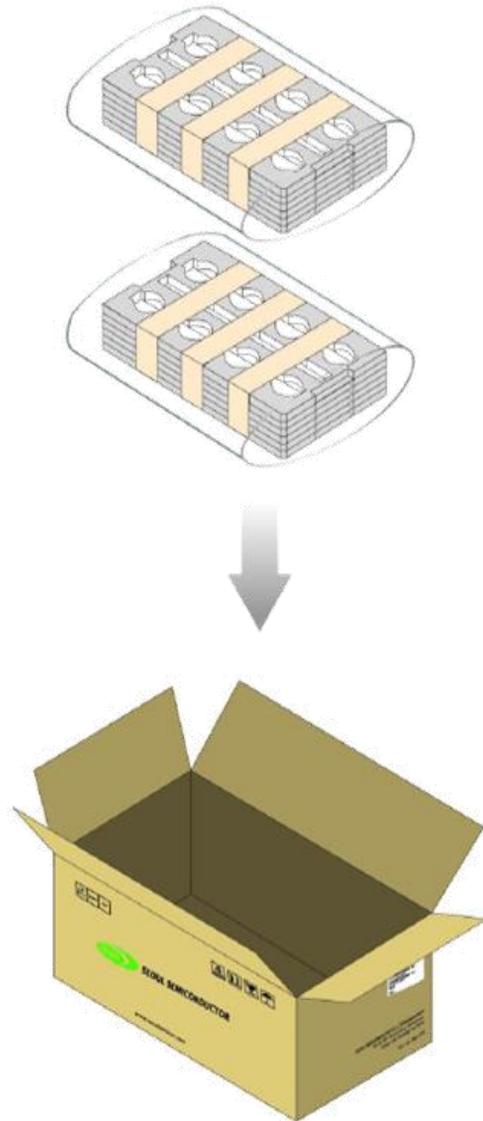


- 20 LED module trays and additional 1 dummy trays up of box
- Add silica gel (1EA) on top of the tray

3. Sealing packing



4. Box information & packing



- 160 PCS modules per BOX 1EA
- ** 1 Box : 8 PCS per tray x 20 trays = 160 PCS

Notes

- Information for rank mixing
 - Tray and sealing packing should not include rank mixing.
 - Rank mixing is possible in the box.

Label Information

Model No.	SMJD-HE2V10W3 ⁽¹⁾
Rank	XXX ⁽²⁾
Type	
Quantity	XX
Date	YYYY.MM.DD
	SEOUL SEMICONDUCTOR CO.,LTD.

Notes

- (1) The model number designation is explained as follow
SMJD : Seoul Semiconductor internal code
HE : High Efficacy
2V : Input Voltage (2V = 120V)
10W : About Power Consumption
3 : MJT PKG (SAW8KG0B)
- (2) It represents the LED module rank that consists of three characters.
- (3) It is attached to the top left corner of the box.

TOTAL Quantity  XX
 SEOUL SEMICONDUCTOR CO.,LTD.

Notes

- (1) It is attached to the bottom right corner of the box.

Handling of Silicone Resin for LEDs

- (1) Acrich2 series is encapsulated with silicone resin for high optical efficiency.
- (2) Please do not touch the silicone resin area with sharp objects such as pincette(tweezers).
- (3) Finger prints on silicone resin area may affect the performance.
- (4) Please store LEDs in covered containers to prevent dust accumulation as this may affect performance.
- (5) Excessive force more than 3000gf to the silicone lens can result in fatal or permanent damage with LEDs.
- (6) Please do not cover the silicone resin area with any other resins such as epoxy, urethane, etc.

Handling with regards to static electricity

- (1) The Acrich2 products use an integrated circuit (IC) which can be damaged when exposed to static electricity. Please handle using equipment that prevents static electricity. Do not touch unless ESD protection is used.
- (2) The Acrich2 product should also not be installed in end equipment without ESD protection.

Storage before use

- (1) Do not impact or place pressure on this product because even a small amount of pressure can damage the product. The product should also not be placed in high temperatures, high humidity or direct sunlight since the device is sensitive to these conditions.
- (2) When storing devices for a long period of time before usage, please following these guidelines:
 - * The devices should be stored in the anti-static bag that it was shipped in from Seoul-Semiconductor with opening.
 - * If the anti-static bag has been opened, re-seal preventing air and moisture from being present in the bag.

Guidelines for properly working with Acrich2

- (1) Discharge the lighting system a minimum of 2-3 times prior to working with the module.
- (2) Use only properly rated test equipment and tools for the rated voltage and current of the product being tested.
- (3) It is strongly suggested to wear rubber insulated gloves and rubber bottom shoes.
- (4) Do not wear any conductive items (such as jewelry) which could accidentally contact electric circuits.
- (5) Perform several tests with power off and the lighting system unplugged.
- (6) Faults, lightning, or switching transients can cause voltage surges in excess of the normal ratings.
- (7) Internal component failure can cause excessive voltages.
- (8) Stored or residual electricity in long wire could be hazardous.
- (9) Make sure proper discharge prior to starting work.

Precaution for Use

- (1) Please review the Acrich2 Application Note for proper protective circuitry usage.
- (2) Please note, Acrich2 products run off of high voltage, therefore caution should be taken when working near Acrich2 products.
- (3) DO NOT touch any of the circuit board, components or terminals with body or metal while circuit is active.
- (4) Please do not add or change wires while Acrich2 circuit is active.
- (5) Long time exposure to sunlight or UV can cause the lens to discolor.
- (6) Please do not use adhesives to attach the LED that outgas organic vapor.
- (7) Please do not use together with the materials containing Sulfur.
- (8) Please do not assemble in conditions of high moisture and/or oxidizing gas such as Cl, H₂S, NH₃, SO₂, NO_x, etc.
- (9) Please do not make any modification on module.
- (10) Please be cautious when soldering to board so as not to create a short between different trace patterns.
- (11) LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).
Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.

a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to LEDs may cause the product to demonstrate unusual characteristics such as:

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event.

One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

Precaution for Use

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls:

- Humidity control (ESD gets worse in a dry environment)

b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device.

The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package
(If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package
(shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires.
- This damage usually appears due to the thermal stress produced during the EOS event.

c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:

- A surge protection circuit
- An appropriately rated over voltage protection device
- A current limiting device



Company Information

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Company Information

Seoul Semiconductor (www.SeoulSemicon.com) manufactures and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, Home appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs.

The company's broad product portfolio includes a wide array of package and device choices such as Acrich and Acirch2, high-brightness LEDs, mid-power LEDs, side-view LEDs, and through-hole type LEDs as well as custom modules, displays, and sensors.

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